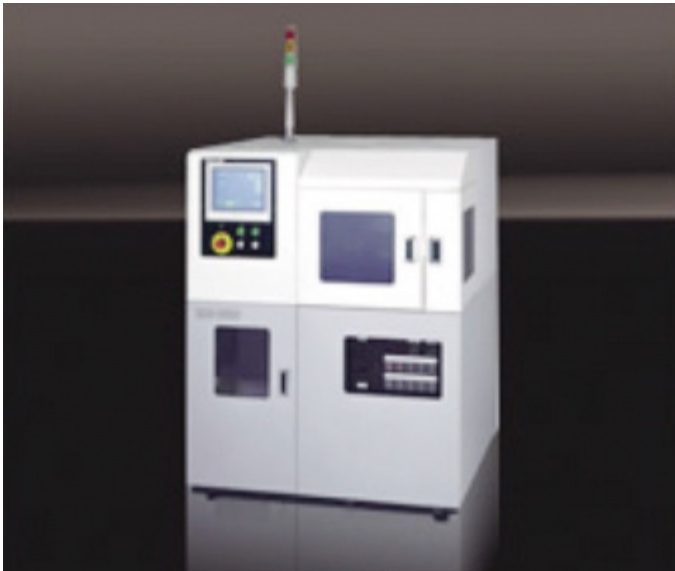


200mm Fully-Automatic BG Tape Remover

# RAD-3000F/8



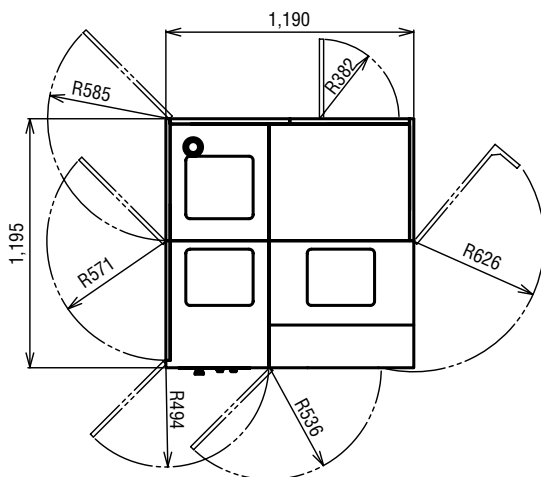
## Outline

- Fully-automatic BG Tape remover for single wafer.
- After alignment, UV is irradiated when necessary, and back grinding tape is removed by attaching heat seal on the periphery of the wafer, fixed with heater.

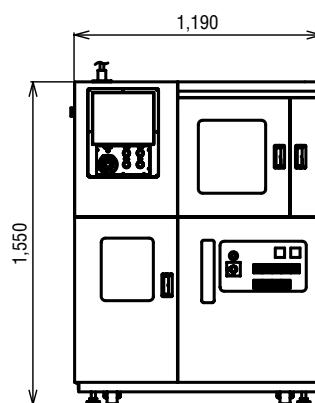
**Option** ·Host Communication Function (Communication Format :  
Conforms to SECS-I and HSMS/Software : Conforms to GEM)

**Suitable Tapes** ·BG Tape : Adwill E series, P series

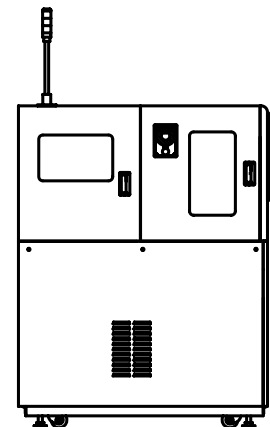
## External View



Top View



Front View



Left Side View

Unit:mm

## Facility

<b>Power Supply</b>	Voltage	: AC200-230V ±10% (AC190-253V)
	Frequency	: 50/60Hz
	Phase	: single phase
	Power consumption	: 5.0kW
<b>Air Supply</b>	Air pressure	: 0.5-0.8MPa
	Air consumption	: >150L/min (ANR)
<b>Vacuum Supply</b>	Vacuum pressure	: >-80kPa

**Applicable Wafer Size** 125mm, 150mm, 200mm

**Size**  
Width : 1,190mm  
Depth : 1,195mm  
Height : 1,550mm  
(excluding the signal tower)

**Weight** 1,000kg

**UPH** 80wafers/hour

The above processing capacity is based on following conditions:

Wafer : 200mm diameter non-polished mirror wafer  
Back grinding tape : E-6142S from LINTEC



**LINTEC Corporation** *Linking your dreams*

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